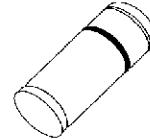


## SMALL SIGNAL SCHOTTKY DIODE


**MINIMELF**  
 (Glass)

### DESCRIPTION

Metal to silicon junction diode primarily intended for UHF mixers and ultrafast switching applications.

### ABSOLUTE MAXIMUM RATINGS (limiting values)

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive Peak Reverse Voltage		5	V
$I_F$	Forward Continuous Current	$T_i = 25^\circ\text{C}$	30	mA
$I_{FSM}$	Surge non Repetitive Forward Current	$t_p \leq 1\text{s}$	60	mA
$T_{stg}$ $T_j$	Storage and Junction Temperature Range		- 65 to +150 - 65 to +125	$^\circ\text{C}$ $^\circ\text{C}$
$T_L$	Maximum Temperature for Soldering during 15s		260	$^\circ\text{C}$

### THERMAL RESISTANCE

Symbol	Test Conditions	Value	Unit
$R_{th(j-l)}$	Junction-leads	400	$^\circ\text{C}/\text{W}$

### ELECTRICAL CHARACTERISTICS

#### STATIC CHARACTERISTICS

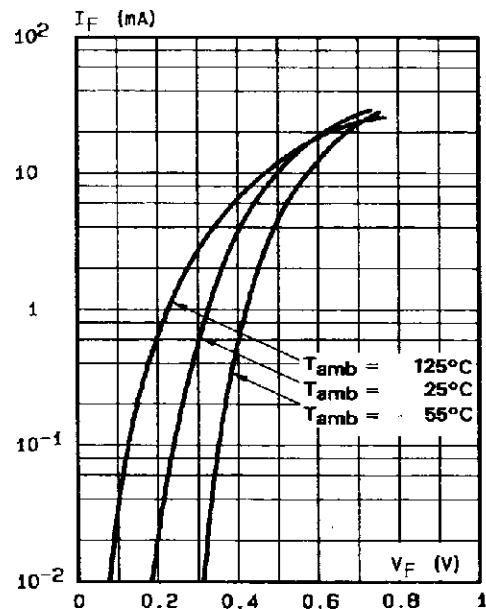
Symbol	Test Conditions		Min.	Typ.	Max.	Unit
$V_{BR}$	$T_{amb} = 25^\circ\text{C}$	$I_R = 100\mu\text{A}$	5			V
$V_F$ (1)	$T_{amb} = 25^\circ\text{C}$	$I_F = 10\text{mA}$			0.55	V
$I_R$ (1)	$T_{amb} = 25^\circ\text{C}$	$V_R = 1\text{V}$			0.05	$\mu\text{A}$

#### DYNAMIC CHARACTERISTICS

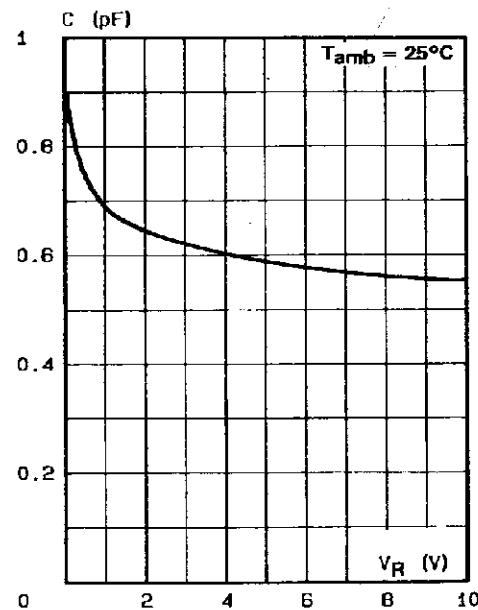
Symbol	Test Conditions			Min.	Typ.	Max.	Unit
C	$T_{amb} = 25^\circ\text{C}$	$V_R = 0\text{V}$	$f = 1\text{GHz}$			1	pF
$Q_s$ (2)	$T_{amb} = 25^\circ\text{C}$	$I_F = 10\text{mA}$				3	pC
F (3)	$T_{amb} = 25^\circ\text{C}$	$f = 1\text{GHz}$		6	7		dB

- (1) Pulse test:  $t_p \leq 300\mu\text{s}$   $\delta < 2\%$ .
- (2) Measured on B-line Electronics QS-3 stored charge meter.
- (3) Noise figure test :
  - diode is inserted in a tuned stripline circuit
  - local oscillator frequency 1GHz
  - local oscillator power 1mW

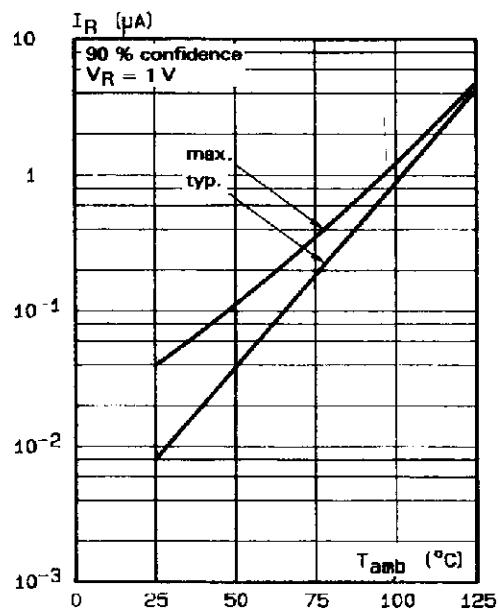
**Figure 1. Forward current versus forward voltage (typical values).**



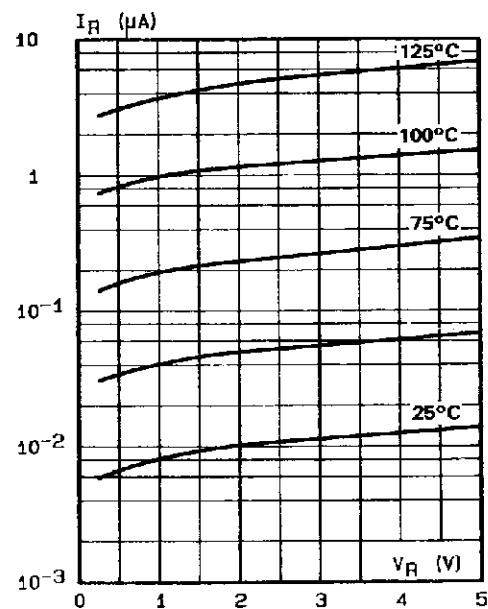
**Figure 2. Capacitance C versus reverse applied voltage  $V_R$  (typical values).**



**Figure 3. Reverse current versus ambient temperature.**

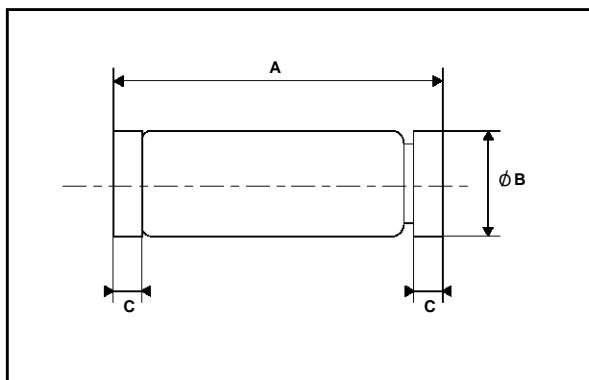


**Figure 4. Reverse current versus continuous reverse voltage (typical values).**

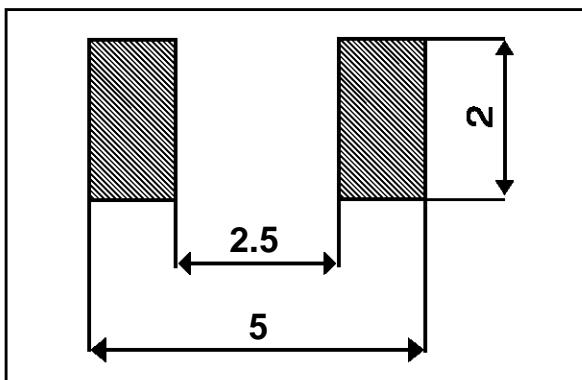


## PACKAGE MECHANICAL DATA

MINIMELF Glass



## FOOT PRINT DIMENSIONS (Millimeter)



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	3.3	3.6	0.130	0.142
B	1.59	1.62	0.063	0.064
C	0.4	0.5	0.016	0.020

Marking: ring at cathode end.  
Weight: 0.05g

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